



# AKM Semiconductor, Inc.

## Product Change Notice

Document ID : AKMSPK170921C  
Product affected : See page 2 (TSSOP-16 Package)  
Date of notification : 9/21/2017  
Type of change : Assembly site  
Reason for change : Closure of current assembly line

### Description of change:

Asahi Kasei Microdevices Corp. (AKM) will transfer assembly process for the products which are currently assembled by one of our package vendors, Kato Electric Yamanashi plant due to its assembly line closure. Detailed information on schedule and new assembly site are attached to this notice. There is no change with customer ordering part number.

### Affected Product and Schedule of New Part

See page 2

### Comparison of current and new part

See page 3 to 6

AKM will consider this notice fully noticed and approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice.

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## Comparison Chart (TSSOP-16)

Changes are highlighted in yellow.

### 1 Affected Part

See page 2

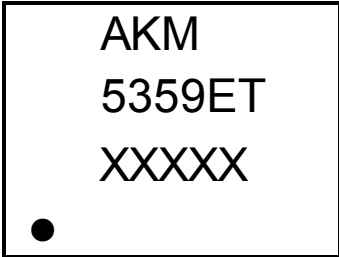
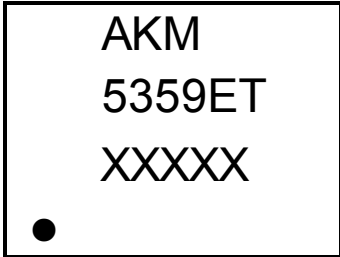
### 2 Process Flow

Process flow	Current	New
Wafer fabrication	AKM FAB2 (No Change)	
Probe test		
Back grind		
Dicing	↓	↓
Die bonding	KATOH Electric. Co.,Ltd.(Yamanashi)	KATOH Electric. Co.,Ltd.(Miyagi)
Wire bonding		
Molding		
Plating	OKURA MICRO-COATING Co.,LTD.	KEDICA Co.,LTD.
Marking		
Trim & Form		
Final test	↓	↓
Taping	AKM FAB2 (No Change)	
Shipping		

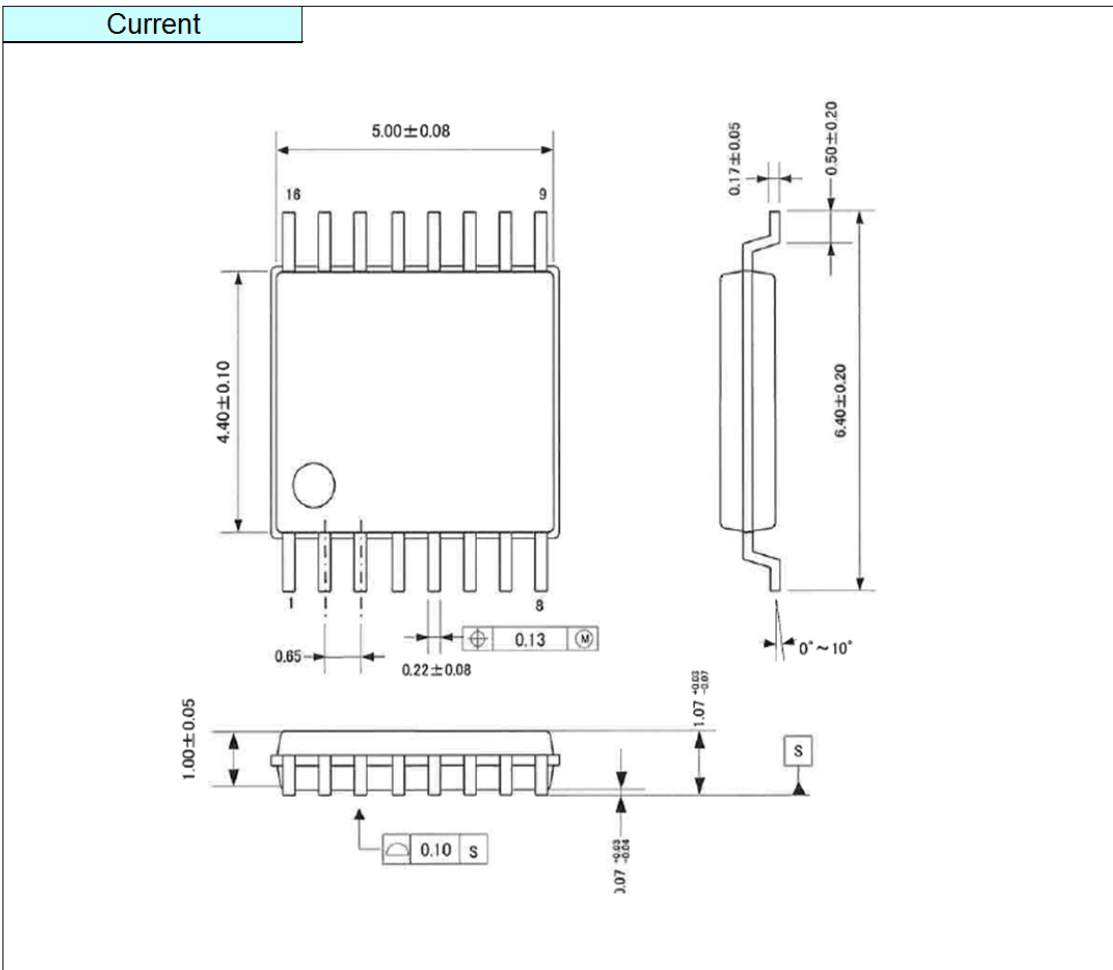
### 3 Specifications

	Current	New
Package type	TSSOP	no change
Pin count	16	no change
Die information	Thickness : 280μm	Thickness : no change
Lead frame	Material : Cu	Material : no change
	Base material : C194	Base material : no change
	Die pad : 2.80 x 3.50 mm	Die pad : no change
Dia attach material	Type : Ag paste	Type : no change
	Supplier : Hitachi Chemical	Supplier : no change
Wire	Diameter : φ20-25μm	Diameter : no change
	Purity : 4N	Purity : no change
Mold compound	Type : Epoxy resin	Type : no change
	Supplier : Hitachi Chemical	Supplier : no change
	Halogen free : No	Halogen free : Yes
Plating	Composition : Sn-Bi (Bi: 2±1%)	Composition : no change
	Thickness : 5~15μm	Thickness : no change
Packing	T&R 1000pcs/Reel	no change

### 4 Laser Marking

	Current	New
Marking type	Type : Laser	Type : no change
Marking specification	Line 1 : AKM	Line 1 : no change
	Line 2 : (Device name)	Line 2 : no change
	Line 3 : (Datecode)	Line 3 : no change
	Digits of datecode : 5	Digits of datecode : no change
Index marking	Pin#1	no change
Marking layout *Example of AK5359ET		

## 5 Package Dimensions



**New**

No Change

Item		Current	New
PKG height	mm	1.07+0.03/-0.07	no change
Standoff	mm	0.07+0.03/-0.04	no change
<b>Lead thickness</b>	mm	0.17±0.05	no change
<b>Lead width</b>	mm	0.22±0.08	no change
<b>PKG width(X)</b>	mm	5.0±0.08	no change
<b>PKG width(Y)</b>	mm	4.4±0.10	no change
<b>Lead pitch</b>	mm	0.65	no change
<b>Tip length of lead</b>	mm	0.50±0.20	no change
Tolerance of lead position	mm	0.13	no change
<b>Coplanarity</b>	mm	0.1	no change

6 Recommended Solder Pad Dimensions

Current	New
<p>The diagram shows a top-down view of a solder pad. It consists of two rows of eight rectangular pads each. The pads are arranged symmetrically about a vertical centerline. Dimensions are as follows: the top row pads are 0.10 units high and 0.90 units wide; the bottom row pads are 0.40 units high and 0.65 units wide; the distance between the centerlines of the two rows is 3.20 units; the total width of the pad area is 6.40 units; and the total length of the pad area is 4.55 units.</p>	<p>No Change</p>

7 Assembly Site Address

Current	Fujiyoshida-City, Yamanashi
New	Rifu-cho, Miyagi-gun, Miyagi